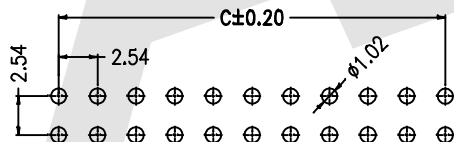
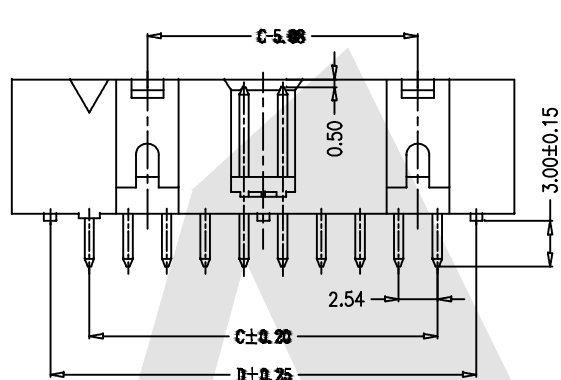
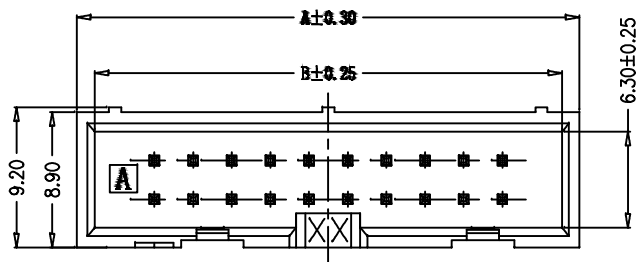
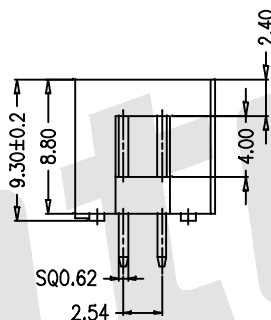


HSF  R6HS



PCB LAYOUT (RECOMMENDED)
(TOP VIEW TOL. ±0.05)



PIN	A	B	C	D	PIN	A	B	C	D
10P	20.20	18.00	10.16	15.30	34P	50.78	48.48	40.64	45.78
14P	25.38	23.08	15.24	20.38	40P	58.40	56.10	48.26	53.40
16P	27.92	25.62	17.78	22.92	50P	71.10	68.80	60.96	66.1
20P	33.00	30.70	22.86	28.00	60P	83.80	81.50	73.66	78.8
26P	40.62	38.32	30.48	35.62	64P	88.88	86.58	78.74	83.88

SPECIFICATION

Current Rating: 3.0Amp
Insulation Resistance: 1000MΩ min
Contact Resistance: 10MΩ max
Withstand Voltage: 500V AC/DC
Operating Temperature: -55°C to +125°C

MATERIAL

Housing: PBT.Glass filled UL94V-0
Contact Material: Brass
Contact Plating:
T= Tin plated on all area, ni under plated all over.
G= Gold plated on all area, ni under plated all over.
L= 0.4u" (Gold)
N= 3u" (Gold)

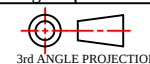
Ordering Code:

BHDS08 - X - X - X - X - X
① ② ③ ④ ⑤ ⑥

- ① Series No:
② No. of Contacts
10 14 16 20
26 34 40 50
60 64
③ Contact Plating:
G0: Gold flash S0: Selective
G1: 3u" Gold S1: Selective 3u"
G2: 5u" Gold S2: Selective 5u"
G3: 10u" Gold S3: Selective 10u"
G4: 15u" Gold S4: Selective 15u"
G5: 30u" Gold S5: Selective 30u"
SN: Tin
④ Color Insulator
B: Black
U: Blue
G: Gray
⑤ Insulator Material
A: PBT
B: PA6T
C: LCP
D: PA46
E: PA9T
⑥ Packing
A: Tray
B: Bag
T: Tube
U: Tube+CAP
R: Tape&Reel
W: Tape&Reel+CAP

Unless Otherwise specified tolerance
X.±0.35 X.XX:±0.20
X.X:±0.25 X.XXX:±0.15

SCALE: As Shown UNIT: mm
DRAW YG ZHONG DATE 01/05/2016
CHECK Bob Yang DATE 01/05/2016



 ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE:
2.54mm Box Header 180° H=9.3

DRAWING NO: BHDS08-XXXXX
PRODUCT NO: BHDS08-XXXXX

REV DESCRIPTION

DATE